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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	3KB (2K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	73 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c58b-40-ss

4.4 RC Oscillator

For timing insensitive applications, the RC device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (R_{EXT}) and capacitor (C_{EXT}) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low C_{EXT} values. The user also needs to take into account variation due to tolerance of external R and C components used.

Figure 4-5 shows how the R/C combination is connected to the PIC16C5X. For R_{EXT} values below 2.2 k Ω , the oscillator operation may become unstable, or stop completely. For very high R_{EXT} values (e.g., 1 M Ω) the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend keeping R_{EXT} between 3 k Ω and 100 k Ω .

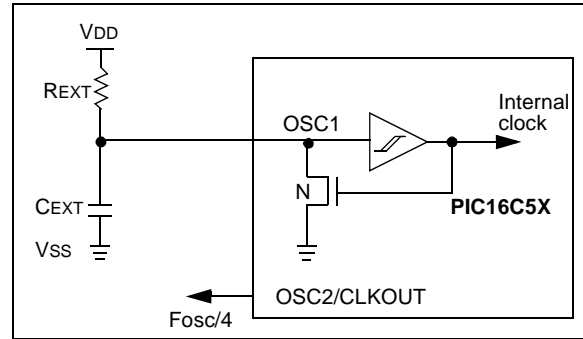
Although the oscillator will operate with no external capacitor ($C_{EXT} = 0$ pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

The Electrical Specifications sections show RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

Also, see the Electrical Specifications sections for variation of oscillator frequency due to V_{DD} for given R_{EXT}/C_{EXT} values as well as frequency variation due to operating temperature for given R, C, and V_{DD} values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin, and can be used for test purposes or to synchronize other logic.

FIGURE 4-5: RC OSCILLATOR MODE



Note: If you change from this device to another device, please verify oscillator characteristics in your application.

PIC16C5X

6.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and peripheral functions to control the operation of the device (Table 6-1).

The Special Registers can be classified into two sets. The Special Function Registers associated with the “core” functions are described in this section. Those related to the operation of the peripheral features are described in the section for each peripheral feature.

TABLE 6-1: SPECIAL FUNCTION REGISTER SUMMARY

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Details on Page
N/A	TRIS	I/O Control Registers (TRISA, TRISB, TRISC)								1111 1111	35
N/A	OPTION	Contains control bits to configure Timer0 and Timer0/WDT prescaler								--11 1111	30
00h	INDF	Uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	32
01h	TMR0	Timer0 Module Register								xxxx xxxx	38
02h ⁽¹⁾	PCL	Low order 8 bits of PC								1111 1111	31
03h	STATUS	PA2	PA1	PA0	\overline{TO}	\overline{PD}	Z	DC	C	0001 1xxx	29
04h	FSR	Indirect data memory address pointer								1xxx xxxx ⁽³⁾	32
05h	PORTA	—	—	—	—	RA3	RA2	RA1	RA0	---- xxxx	35
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	35
07h ⁽²⁾	PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	35

Legend: x = unknown, u = unchanged, — = unimplemented, read as '0' (if applicable). Shaded cells = unimplemented or unused

- Note 1:** The upper byte of the Program Counter is not directly accessible. See Section 6.5 for an explanation of how to access these bits.
- 2:** File address 07h is a General Purpose Register on the PIC16C54, PIC16CR54, PIC16C56, PIC16CR56, PIC16C58 and PIC16CR58.
- 3:** These values are valid for PIC16C57/CR57/C58/CR58. For the PIC16C54/CR54/C55/C56/CR56, the value on RESET is 111x xxxx and for \overline{MCLR} and WDT Reset, the value is 111u uuuu.

7.6 I/O Programming Considerations

7.6.1 BI-DIRECTIONAL I/O PORTS

Some instructions operate internally as read followed by write operations. The BCF and BSF instructions, for example, read the entire port into the CPU, execute the bit operation and re-write the result. Caution must be used when these instructions are applied to a port where one or more pins are used as input/outputs. For example, a BSF operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU, bit5 to be set and the PORTB value to be written to the output latches. If another bit of PORTB is used as a bi-directional I/O pin (say bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and rewritten to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the Input mode, no problem occurs. However, if bit0 is switched into Output mode later on, the content of the data latch may now be unknown.

Example 7-1 shows the effect of two sequential read-modify-write instructions (e.g., BCF, BSF, etc.) on an I/O port.

A pin actively outputting a high or a low should not be driven from external devices at the same time in order to change the level on this pin ("wired-or", "wired-and"). The resulting high output currents may damage the chip.

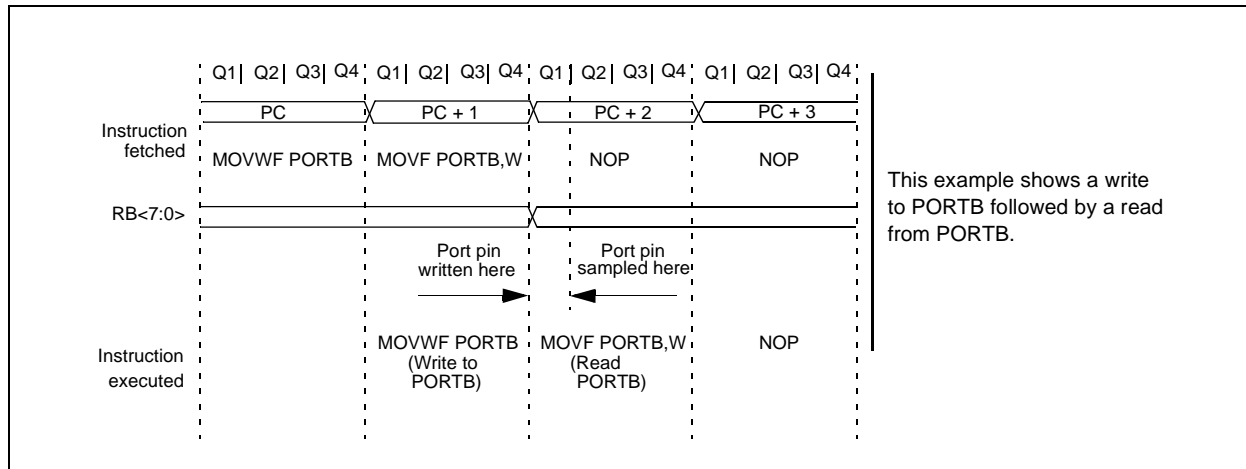
EXAMPLE 7-1: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

```
;Initial PORT Settings
; PORTB<7:4> Inputs
; PORTB<3:0> Outputs
;PORTB<7:6> have external pull-ups and are
;not connected to other circuitry
;
;
;          PORT latch  PORT pins
;          -----
BCF  PORTB, 7  ;01pp pppp  11pp pppp
BCF  PORTB, 6  ;10pp pppp  11pp pppp
MOVLW H'3F'    ;
TRIS  PORTB    ;10pp pppp  10pp pppp
;
;Note that the user may have expected the pin
;values to be 00pp pppp. The 2nd BCF caused
;RB7 to be latched as the pin value (High).
```

7.6.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 7-2). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should allow the pin voltage to stabilize (load dependent) before the next instruction, which causes that file to be read into the CPU, is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a NOP or another instruction not accessing this I/O port.

FIGURE 7-2: SUCCESSIVE I/O OPERATION



8.1 Using Timer0 with an External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (Tosc) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

8.1.1 EXTERNAL CLOCK SYNCHRONIZATION

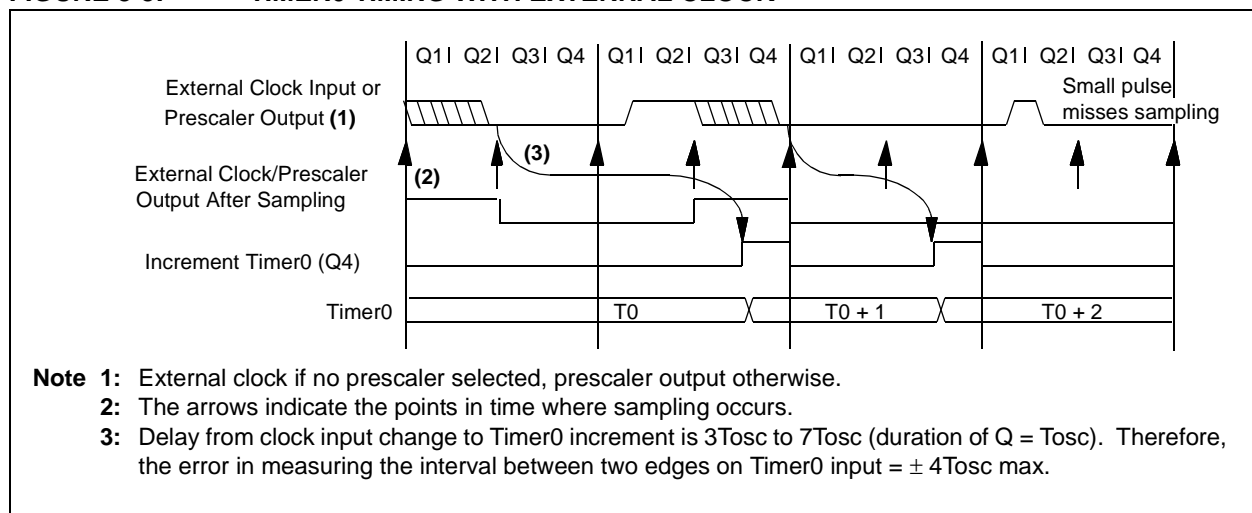
When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 8-5). Therefore, it is necessary for T0CKI to be high for at least $2T_{osc}$ (and a small RC delay of 20 ns) and low for at least $2T_{osc}$ (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

When a prescaler is used, the external clock input is divided by the asynchronous ripple counter-type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least $4T_{osc}$ (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

8.1.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 8-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 8-5: TIMER0 TIMING WITH EXTERNAL CLOCK



PIC16C5X

NOTES:

10.0 INSTRUCTION SET SUMMARY

Each PIC16C5X instruction is a 12-bit word divided into an OPCODE, which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16C5X instruction set summary in Table 10-2 groups the instructions into byte-oriented, bit-oriented, and literal and control operations. Table 10-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator is used to specify which one of the 32 file registers in that bank is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an 8 or 9-bit constant or literal value.

TABLE 10-1: OPCODE FIELD DESCRIPTIONS

Field	Description
<i>f</i>	Register file address (0x00 to 0x1F)
<i>W</i>	Working register (accumulator)
<i>b</i>	Bit address within an 8-bit file register
<i>k</i>	Literal field, constant data or label
<i>x</i>	Don't care location (= 0 or 1) The assembler will generate code with <i>x</i> = 0. It is the recommended form of use for compatibility with all Microchip software tools.
<i>d</i>	Destination select; d = 0 (store result in W) d = 1 (store result in file register 'f') Default is d = 1
<i>label</i>	Label name
<i>TOS</i>	Top of Stack
<i>PC</i>	Program Counter
<i>WDT</i>	Watchdog Timer Counter
<i>TO</i>	Time-out bit
<i>PD</i>	Power-down bit
<i>dest</i>	Destination, either the W register or the specified register file location
[]	Options
()	Contents
→	Assigned to
< >	Register bit field
∈	In the set of
<i>italics</i>	User defined term (font is courier)

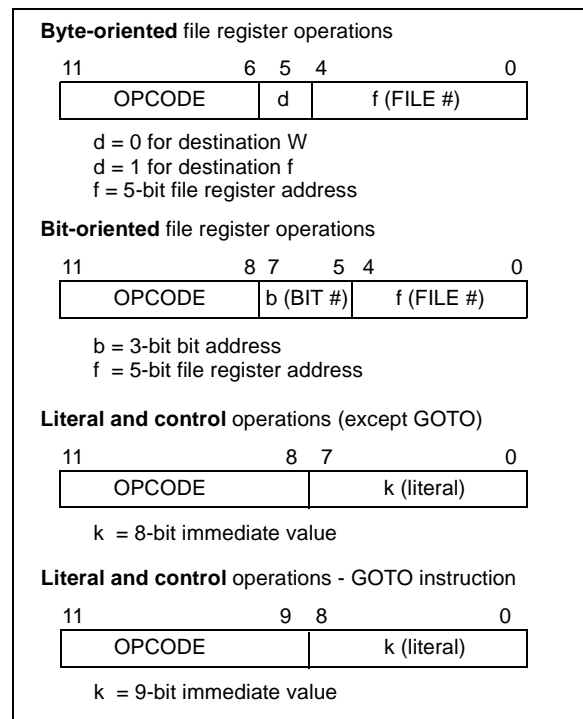
All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time would be 1 μs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time would be 2 μs.

Figure 10-1 shows the three general formats that the instructions can have. All examples in the figure use the following format to represent a hexadecimal number:

0xhhh

where 'h' signifies a hexadecimal digit.

FIGURE 10-1: GENERAL FORMAT FOR INSTRUCTIONS



CALL		Subroutine Call				
Syntax:	[<i>label</i>] CALL k					
Operands:	0 ≤ k ≤ 255					
Operation:	(PC) + 1 → TOS; k → PC<7:0>; (STATUS<6:5>) → PC<10:9>; 0 → PC<8>					
Status Affected:	None					
Encoding:	<table border="1"><tr><td>1001</td><td>kkkk</td><td>kkkk</td></tr></table>			1001	kkkk	kkkk
1001	kkkk	kkkk				
Description:	Subroutine call. First, return address (PC+1) is pushed onto the stack. The eight bit immediate address is loaded into PC bits <7:0>. The upper bits PC<10:9> are loaded from STATUS<6:5>, PC<8> is cleared. CALL is a two-cycle instruction.					
Words:	1					
Cycles:	2					
Example:	HERE CALL THERE					
Before Instruction						
PC = address (HERE)						
After Instruction						
PC = address (THERE)						
TOS = address (HERE + 1)						

CLRF	Clear f			
Syntax:	[<i>label</i>] CLRF f			
Operands:	$0 \leq f \leq 31$			
Operation:	00h \rightarrow (f); 1 \rightarrow Z			
Status Affected:	Z			
Encoding:	<table border="1"><tr><td>0000</td><td>011f</td><td>ffff</td></tr></table>	0000	011f	ffff
0000	011f	ffff		
Description:	The contents of register 'f' are cleared and the Z bit is set.			
Words:	1			
Cycles:	1			
Example:	CLRF FLAG_REG			
Before Instruction				
FLAG_REG	= 0x5A			
After Instruction				
FLAG_REG	= 0x00			
Z	= 1			

CLR W				
Syntax:	[<i>label</i>] CLRW			
Operands:	None			
Operation:	00h → (W); 1 → Z			
Status Affected:	Z			
Encoding:	<table border="1"><tr><td>0000</td><td>0100</td><td>0000</td></tr></table>	0000	0100	0000
0000	0100	0000		
Description:	The W register is cleared. Zero bit (Z) is set.			
Words:	1			
Cycles:	1			
Example:	CLR W			
Before Instruction				
W	= 0x5A			
After Instruction				
W	= 0x00			
Z	= 1			

CLRWD	Clear Watchdog Timer			
Syntax:	[<i>label</i>] CLRWD			
Operands:	None			
Operation:	00h → WDT; 0 → WDT prescaler (if assigned); 1 → \overline{TO} ; 1 → \overline{PD}			
Status Affected:	\overline{TO} , \overline{PD}			
Encoding:	<table border="1"><tr><td>0000</td><td>0000</td><td>0100</td></tr></table>	0000	0000	0100
0000	0000	0100		
Description:	The CLRWD instruction resets the WDT. It also resets the prescaler, if the prescaler is assigned to the WDT and not Timer0. Status bits \overline{TO} and \overline{PD} are set.			
Words:	1			
Cycles:	1			
Example:	CLRWD			
Before Instruction				
WDT counter	= ?			
After Instruction				
WDT counter	= 0x00			
WDT prescaler	= 0			
\overline{TO}	= 1			
\overline{PD}	= 1			

PIC16C5X

COMF Complement f

Syntax: [*label*] COMF f,d

Operands: $0 \leq f \leq 31$
 $d \in [0,1]$

Operation: $(f) \rightarrow (dest)$

Status Affected: Z

Encoding:

0010	01df	ffff
------	------	------

Description: The contents of register 'f' are complemented. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example: COMF REG1, 0

Before Instruction

REG1 = 0x13

After Instruction

REG1 = 0x13

W = 0xEC

DECFSZ Decrement f

Syntax: [*label*] DECFSZ f,d

Operands: $0 \leq f \leq 31$
 $d \in [0,1]$

Operation: $(f) - 1 \rightarrow (dest)$

Status Affected: Z

Encoding:

0000	11df	ffff
------	------	------

Description: Decrement register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example: DECFSZ CNT, 1

Before Instruction

CNT = 0x01

Z = 0

After Instruction

CNT = 0x00

Z = 1

DECFSZ Decrement f, Skip if 0

Syntax: [*label*] DECFSZ f,d

Operands: $0 \leq f \leq 31$
 $d \in [0,1]$

Operation: $(f) - 1 \rightarrow d$; skip if result = 0

Status Affected: None

Encoding:

0010	11df	ffff
------	------	------

Description: The contents of register 'f' are decremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.
 If the result is 0, the next instruction, which is already fetched, is discarded and a NOP is executed instead making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example: HERE DECFSZ CNT, 1

GOTO LOOP

CONTINUE •

•

•

Before Instruction

PC = address (HERE)

After Instruction

CNT = CNT - 1;

if CNT = 0,

PC = address (CONTINUE);

if CNT \neq 0,

PC = address (HERE+1)

PIC16C5X

RLF Rotate Left f through Carry

Syntax: [label] RLF f,d

Operands: $0 \leq f \leq 31$
 $d \in [0,1]$

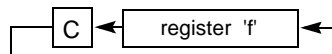
Operation: See description below

Status Affected: C

Encoding:

0011	01df	ffff
------	------	------

Description: The contents of register 'f' are rotated one bit to the left through the Carry Flag (STATUS<0>). If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is stored back in register 'f'.



Words: 1

Cycles: 1

Example: RLF REG1,0

Before Instruction

REG1 = 1110 0110
C = 0

After Instruction

REG1 = 1110 0110
W = 1100 1100
C = 1

RRF Rotate Right f through Carry

Syntax: [label] RRF f,d

Operands: $0 \leq f \leq 31$
 $d \in [0,1]$

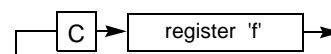
Operation: See description below

Status Affected: C

Encoding:

0011	00df	ffff
------	------	------

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag (STATUS<0>). If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.



Words: 1

Cycles: 1

Example: RRF REG1,0

Before Instruction

REG1 = 1110 0110
C = 0

After Instruction

REG1 = 1110 0110
W = 0111 0011
C = 0

SLEEP Enter SLEEP Mode

Syntax: [label] SLEEP

Operands: None

Operation: 00h → WDT;
0 → WDT prescaler; if assigned
1 → \overline{TO} ;
0 → \overline{PD}

Status Affected: \overline{TO} , \overline{PD}

Encoding:

0000	0000	0011
------	------	------

Description: Time-out status bit (\overline{TO}) is set. The power-down status bit (\overline{PD}) is cleared. The WDT and its prescaler are cleared.
The processor is put into SLEEP mode with the oscillator stopped. See section on SLEEP for more details.

Words: 1

Cycles: 1

Example: SLEEP

12.4 DC Characteristics: PIC16C54/55/56/57-RC, XT, 10, HS, LP (Commercial) PIC16C54/55/56/57-RCI, XTI, 10I, HSI, LPI (Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial –40°C ≤ TA ≤ +85°C for industrial				
Param No.	Symbol	Characteristic/Device	Min	Typ†	Max	Units	Conditions
D030	V _{IL}	Input Low Voltage					
		I/O ports	V _{SS}	—	0.2 V _{DD}	V	Pin at hi-impedance PIC16C5X-RC only ⁽³⁾ PIC16C5X-XT, 10, HS, LP
		MCLR (Schmitt Trigger)	V _{SS}	—	0.15 V _{DD}	V	
		T0CKI (Schmitt Trigger)	V _{SS}	—	0.15 V _{DD}	V	
		OSC1 (Schmitt Trigger)	V _{SS}	—	0.15 V _{DD}	V	
		OSC1 (Schmitt Trigger)	V _{SS}	—	0.3 V _{DD}	V	
D040	V _{IH}	Input High Voltage					
		I/O ports	0.45 V _{DD}	—	V _{DD}	V	For all V _{DD} ⁽⁴⁾ 4.0V < V _{DD} ≤ 5.5V ⁽⁴⁾ V _{DD} > 5.5V
		I/O ports	2.0	—	V _{DD}	V	
		I/O ports	0.36 V _{DD}	—	V _{DD}	V	
		MCLR (Schmitt Trigger)	0.85 V _{DD}	—	V _{DD}	V	
		T0CKI (Schmitt Trigger)	0.85 V _{DD}	—	V _{DD}	V	
		OSC1 (Schmitt Trigger)	0.85 V _{DD}	—	V _{DD}	V	
		OSC1 (Schmitt Trigger)	0.7 V _{DD}	—	V _{DD}	V	PIC16C5X-RC only ⁽³⁾ PIC16C5X-XT, 10, HS, LP
D050	V _{HYS}	Hysteresis of Schmitt Trigger inputs	0.15 V _{DD} *	—	—	V	
D060	I _{IL}	Input Leakage Current^(1,2)					
		I/O ports	–1	0.5	+1	μA	For V_{DD} ≤ 5.5V: V _{SS} ≤ V _{PIN} ≤ V _{DD} , pin at hi-impedance V _{PIN} = V _{SS} + 0.25V V _{PIN} = V _{DD} V _{SS} ≤ V _{PIN} ≤ V _{DD} V _{SS} ≤ V _{PIN} ≤ V _{DD} , PIC16C5X-XT, 10, HS, LP
		MCLR	–5	—	—	μA	
		MCLR	—	0.5	+5	μA	
		T0CKI	–3	0.5	+3	μA	
		OSC1	–3	0.5	+3	μA	
D080	V _{OL}	Output Low Voltage					
		I/O ports	—	—	0.6	V	I _{OL} = 8.7 mA, V _{DD} = 4.5V I _{OL} = 1.6 mA, V _{DD} = 4.5V, PIC16C5X-RC
		OSC2/CLKOUT	—	—	0.6	V	
D090	V _{OH}	Output High Voltage⁽²⁾					
		I/O ports	V _{DD} – 0.7	—	—	V	I _{OH} = –5.4 mA, V _{DD} = 4.5V I _{OH} = –1.0 mA, V _{DD} = 4.5V, PIC16C5X-RC
		OSC2/CLKOUT	V _{DD} – 0.7	—	—	V	

* These parameters are characterized but not tested.

† Data in the Typical (“Typ”) column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/V_{PP} pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

2: Negative current is defined as coming out of the pin.

3: For PIC16C5X-RC devices, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

4: The user may use the better of the two specifications.

PIC16C5X

FIGURE 12-5: TIMER0 CLOCK TIMINGS - PIC16C54/55/56/57

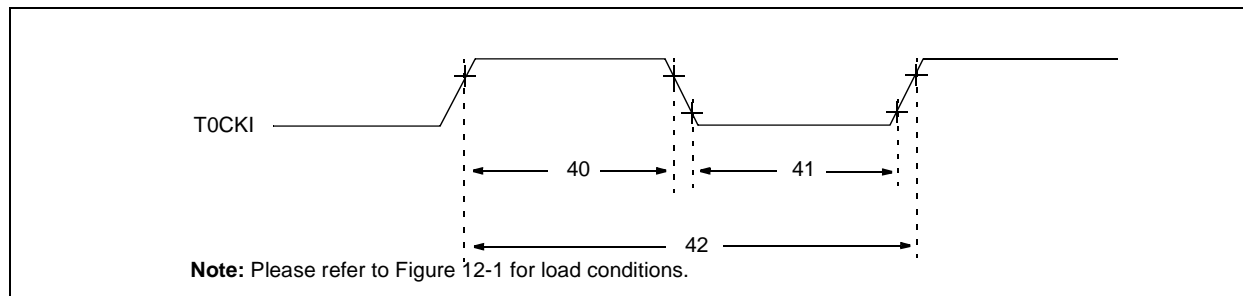


TABLE 12-4: TIMER0 CLOCK REQUIREMENTS - PIC16C54/55/56/57

AC Characteristics		Standard Operating Conditions (unless otherwise specified)					
		Operating Temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended					
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width - No Prescaler	0.5 Tcy + 20*	—	—	ns	
		- With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width - No Prescaler	0.5 Tcy + 20*	—	—	ns	
		- With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period	20 or $\frac{Tcy + 40^*}{N}$	—	—	ns	Whichever is greater. N = Prescale Value (1, 2, 4,..., 256)

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

PIC16C5X

13.2 DC Characteristics: PIC16CR54A-04E, 10E, 20E (Extended)

PIC16CR54A-04E, 10E, 20E (Extended)			Standard Operating Conditions (unless otherwise specified) Operating Temperature $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended				
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage RC, XT and LP modes HS mode	3.25 4.5	— —	6.0 5.5	V V	
D002	VDR	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	Supply Current ⁽²⁾ RC ⁽³⁾ and XT modes HS mode HS mode	— — —	1.8 4.8 9.0	3.3 10 20	mA mA mA	FOSC = 4.0 MHz, VDD = 5.5V FOSC = 10 MHz, VDD = 5.5V FOSC = 16 MHz, VDD = 5.5V
D020	IPD	Power-down Current ⁽²⁾	— —	5.0 0.8	22 18	μA μA	VDD = 3.25V, WDT enabled VDD = 3.25V, WDT disabled

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.

b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

3: Does not include current through REXT. The current through the resistor can be estimated by the formula: $I_R = V_{DD}/2R_{EXT}$ (mA) with REXT in kΩ.

PIC16C5X

FIGURE 13-3: CLKOUT AND I/O TIMING - PIC16CR54A

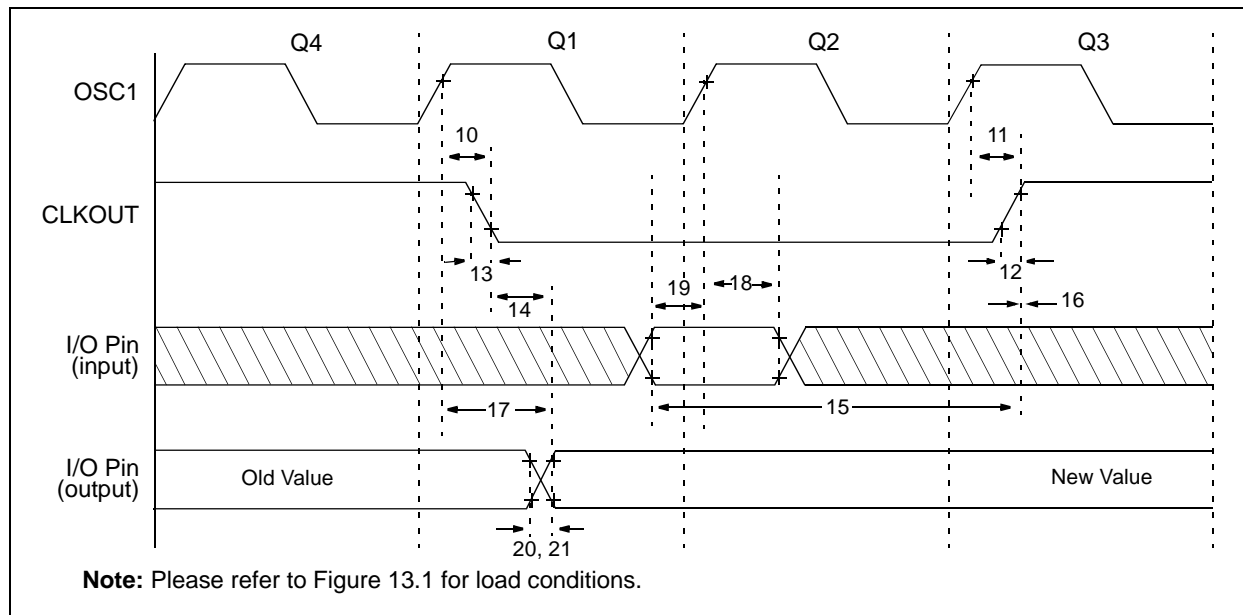


TABLE 13-2: CLKOUT AND I/O TIMING REQUIREMENTS - PIC16CR54A

AC Characteristics		Standard Operating Conditions (unless otherwise specified)				
		Operating Temperature				
		0°C ≤ TA ≤ +70°C for commercial				
		-40°C ≤ TA ≤ +85°C for industrial				
		-40°C ≤ TA ≤ +125°C for extended				
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units
10	TosH2ckL	OSC1↑ to CLKOUT↓ ⁽¹⁾	—	15	30**	ns
11	TosH2ckH	OSC1↑ to CLKOUT↑ ⁽¹⁾	—	15	30**	ns
12	TckR	CLKOUT rise time ⁽¹⁾	—	5.0	15**	ns
13	TckF	CLKOUT fall time ⁽¹⁾	—	5.0	15**	ns
14	TckL2ioV	CLKOUT↓ to Port out valid ⁽¹⁾	—	—	40**	ns
15	TioV2ckH	Port in valid before CLKOUT↑ ⁽¹⁾	0.25 TCY+30*	—	—	ns
16	TckH2ioI	Port in hold after CLKOUT↑ ⁽¹⁾	0*	—	—	ns
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid ⁽²⁾	—	—	100*	ns
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns
20	TioR	Port output rise time ⁽²⁾	—	10	25**	ns
21	TioF	Port output fall time ⁽²⁾	—	10	25**	ns

* These parameters are characterized but not tested.

** These parameters are design targets and are not tested. No characterization data available at this time.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x TOSC.

2: Please refer to Figure 13.1 for load conditions.

FIGURE 14-9: V_{TH} (INPUT THRESHOLD VOLTAGE) OF I/O PINS vs. V_{DD}

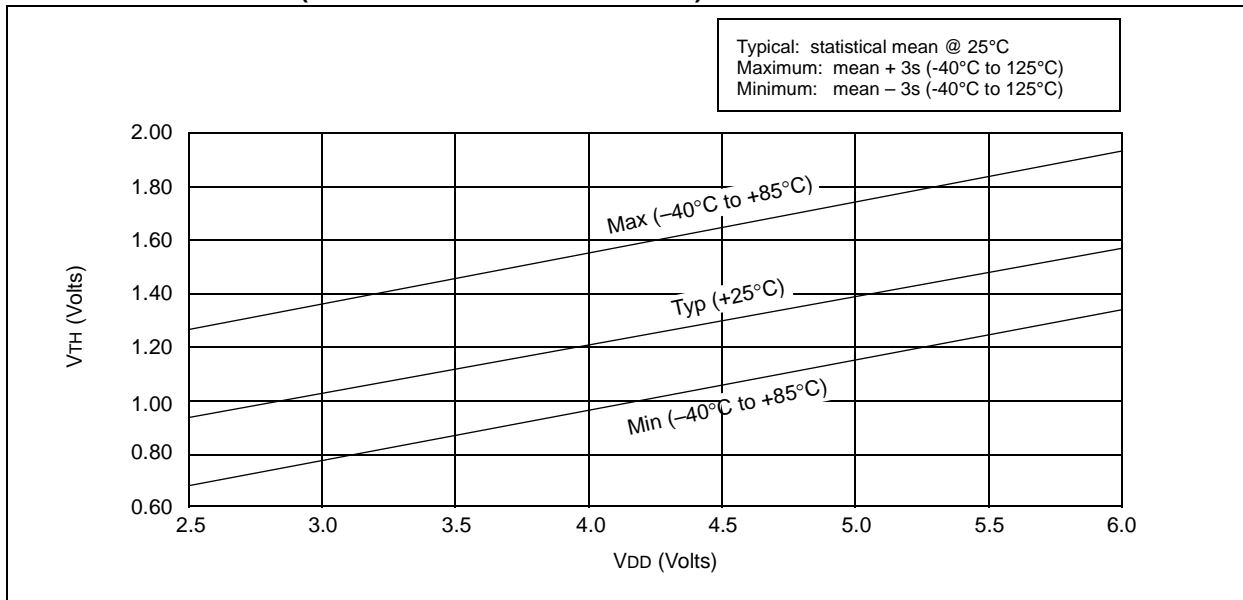


FIGURE 14-10: V_{IH} , V_{IL} OF MCLR, T0CKI AND OSC1 (RC MODE) vs. V_{DD}

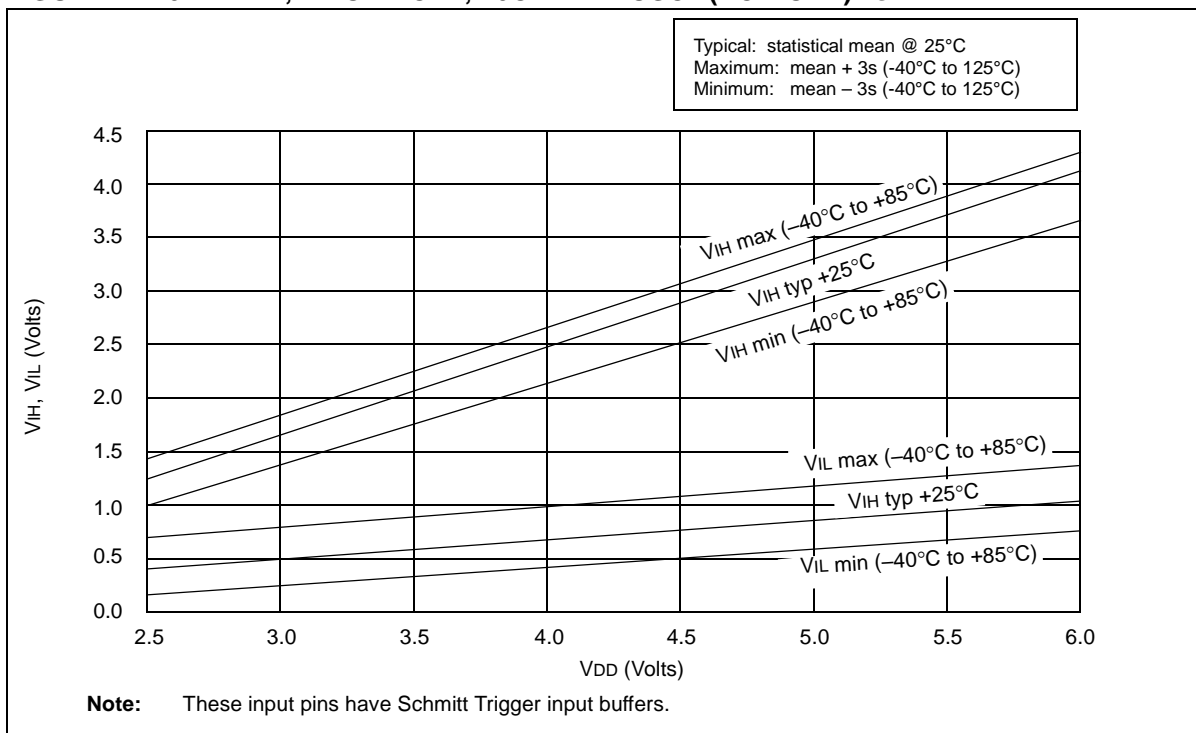


FIGURE 14-19: PORTA, B AND C I_{OH} vs. V_{OH}, V_{DD} = 3 V

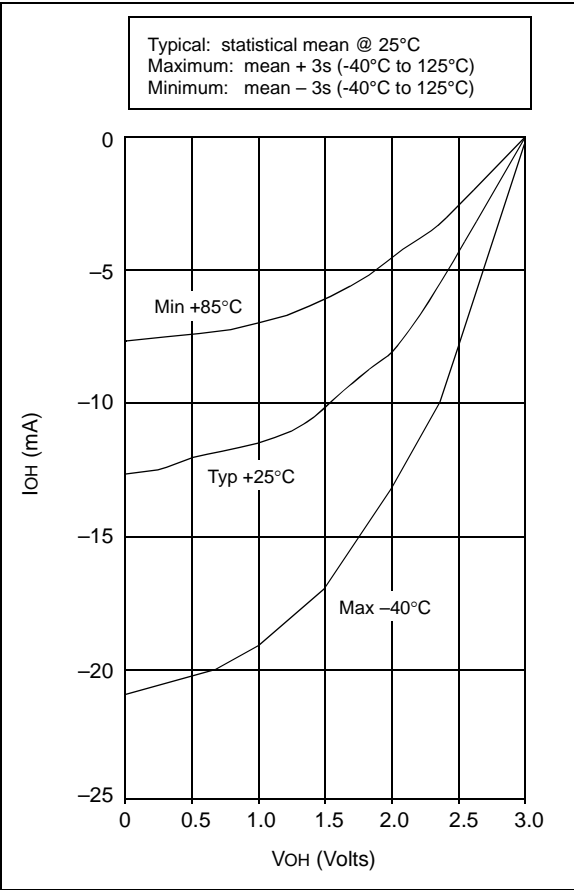
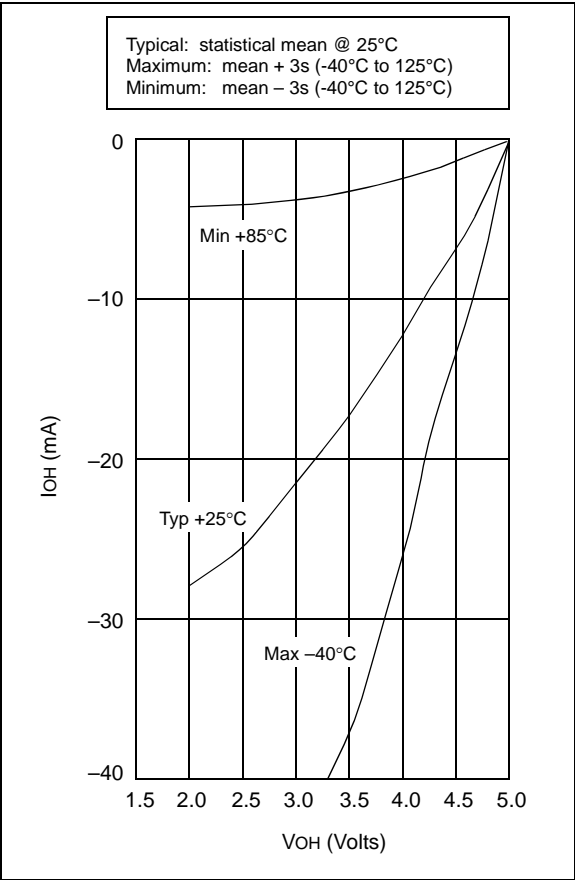


FIGURE 14-20: PORTA, B AND C I_{OH} vs. V_{OH}, V_{DD} = 5 V



PIC16C5X

**TABLE 14-2: INPUT CAPACITANCE FOR
PIC16C54/56**

Pin	Typical Capacitance (pF)	
	18L PDIP	18L SOIC
RA port	5.0	4.3
RB port	5.0	4.3
$\overline{\text{MCLR}}$	17.0	17.0
OSC1	4.0	3.5
OSC2/CLKOUT	4.3	3.5
T0CKI	3.2	2.8

All capacitance values are typical at 25°C. A part-to-part variation of $\pm 25\%$ (three standard deviations) should be taken into account.

**TABLE 14-3: INPUT CAPACITANCE FOR
PIC16C55/57**

Pin	Typical Capacitance (pF)	
	28L PDIP (600 mil)	28L SOIC
RA port	5.2	4.8
RB port	5.6	4.7
RC port	5.0	4.1
$\overline{\text{MCLR}}$	17.0	17.0
OSC1	6.6	3.5
OSC2/CLKOUT	4.6	3.5
T0CKI	4.5	3.5

All capacitance values are typical at 25°C. A part-to-part variation of $\pm 25\%$ (three standard deviations) should be taken into account.

PIC16C5X

17.1 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial) PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial) PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial) PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

PIC16LC5X PIC16LCR5X (Commercial, Industrial)		Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial					
PIC16C5X PIC16CR5X (Commercial, Industrial)		Standard Operating Conditions (unless otherwise specified) Operating Temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial					
Param No.	Symbol	Characteristic/Device	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage					
		PIC16LC5X	2.5	—	5.5	V	-40°C ≤ TA ≤ +85°C, 16LCR5X
			2.7	—	5.5	V	-40°C ≤ TA ≤ 0°C, 16LC5X
			2.5	—	5.5	V	0°C ≤ TA ≤ +85°C 16LC5X
D001A		PIC16C5X	3.0	—	5.5	V	RC, XT, LP and HS mode from 0 - 10 MHz
			4.5	—	5.5	V	from 10 - 20 MHz
D002	VDR	RAM Data Retention Voltage⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C, unless otherwise stated. These parameters are for design guidance only, and are not tested.

- Note 1:** This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
- Note 2:** The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
- a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.
- b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
- Note 3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

PIC16C5X

FIGURE 17-7: CLKOUT AND I/O TIMING - PIC16C5X, PIC16CR5X

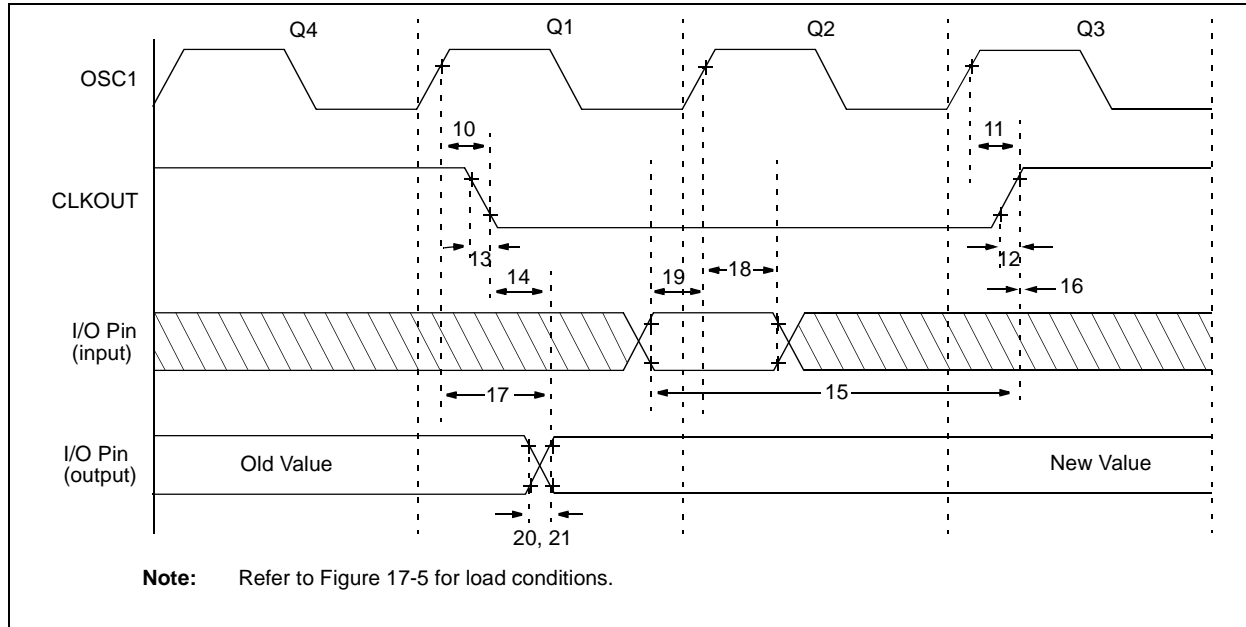


TABLE 17-2: CLKOUT AND I/O TIMING REQUIREMENTS - PIC16C5X, PIC16CR5X

AC Characteristics		Standard Operating Conditions (unless otherwise specified)				
		Operating Temperature				
		0°C ≤ TA ≤ +70°C for commercial				
		-40°C ≤ TA ≤ +85°C for industrial				
		-40°C ≤ TA ≤ +125°C for extended				
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units
10	TosH2ckL	OSC1↑ to CLKOUT↓ ⁽¹⁾	—	15	30**	ns
11	TosH2ckH	OSC1↑ to CLKOUT↑ ⁽¹⁾	—	15	30**	ns
12	TckR	CLKOUT rise time ⁽¹⁾	—	5.0	15**	ns
13	TckF	CLKOUT fall time ⁽¹⁾	—	5.0	15**	ns
14	TckL2ioV	CLKOUT↓ to Port out valid ⁽¹⁾	—	—	40**	ns
15	TioV2ckH	Port in valid before CLKOUT↑ ⁽¹⁾	0.25 TCY+30*	—	—	ns
16	TckH2ioI	Port in hold after CLKOUT↑ ⁽¹⁾	0*	—	—	ns
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid ⁽²⁾	—	—	100*	ns
18	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns
20	TioR	Port output rise time ⁽²⁾	—	10	25**	ns
21	TioF	Port output fall time ⁽²⁾	—	10	25**	ns

* These parameters are characterized but not tested.

** These parameters are design targets and are not tested. No characterization data available at this time.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x TOSC.

2: Refer to Figure 17-5 for load conditions.

FIGURE 18-12: TYPICAL I_{DD} vs. FREQUENCY (WDT DISABLED, RC MODE @ 100 pF, 25°C)

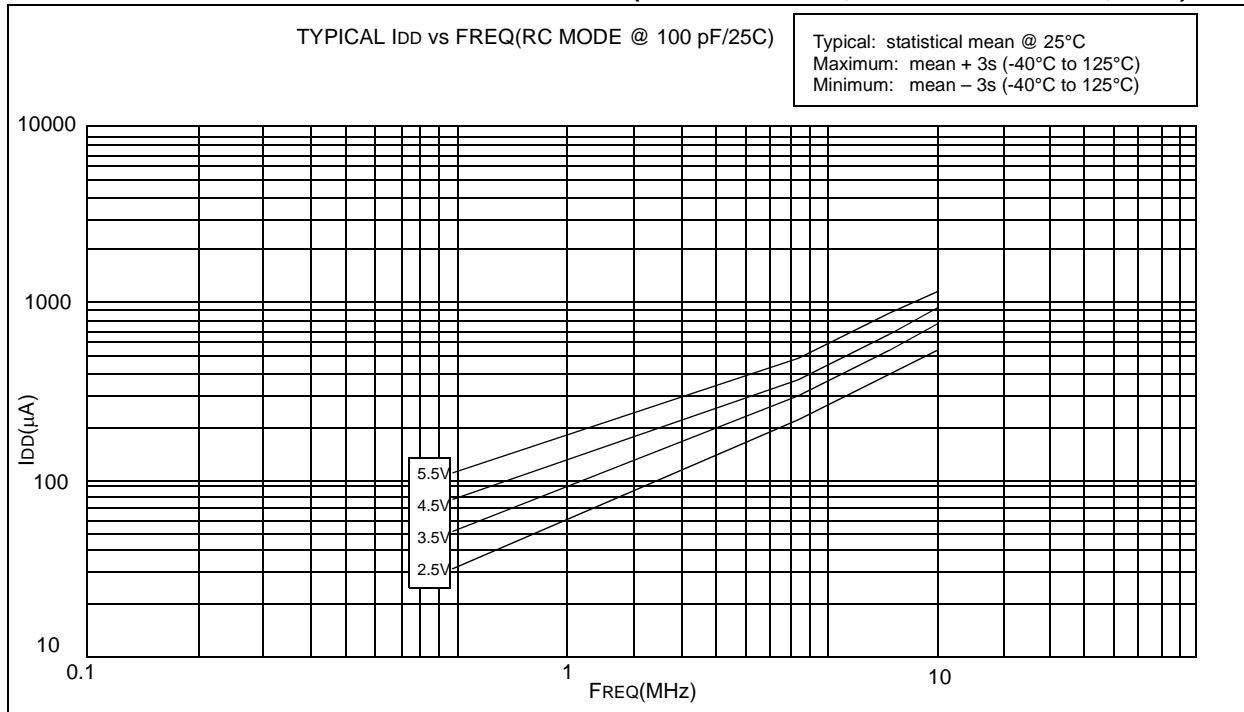
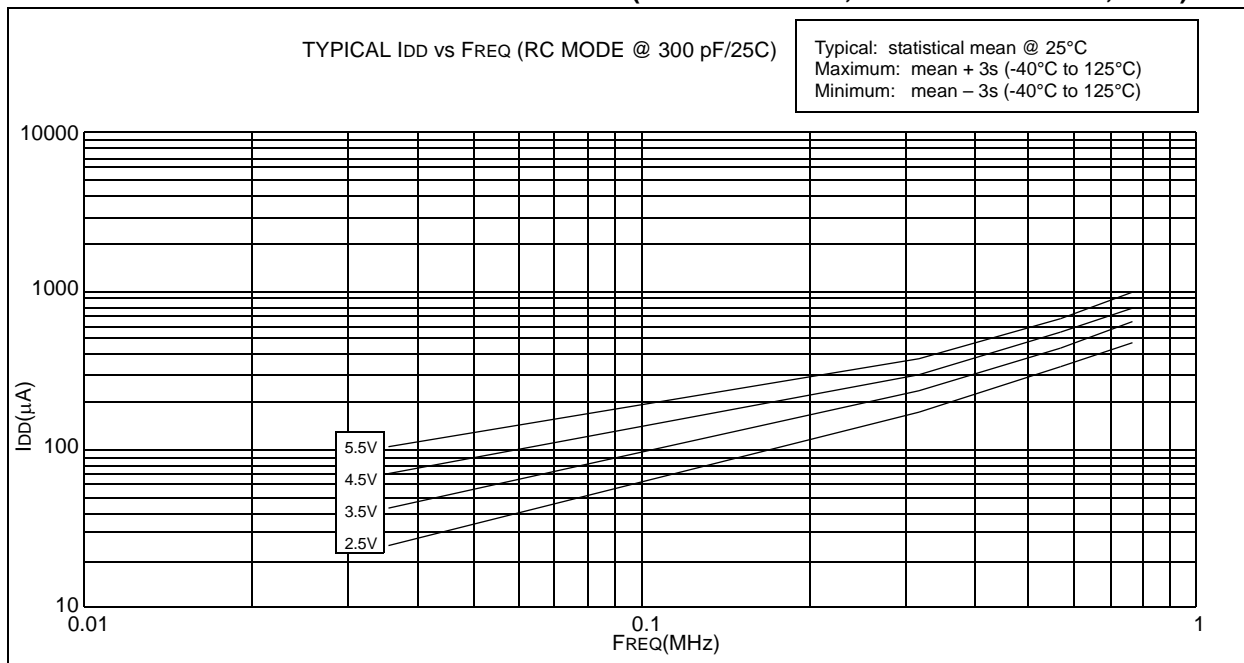


FIGURE 18-13: TYPICAL I_{DD} vs. FREQUENCY (WDT DISABLED, RC MODE @ 300 pF, 25°C)



PIC16C5X

**FIGURE 18-18: PORTA, B AND C IoL vs.
VOL, VDD = 5 V**

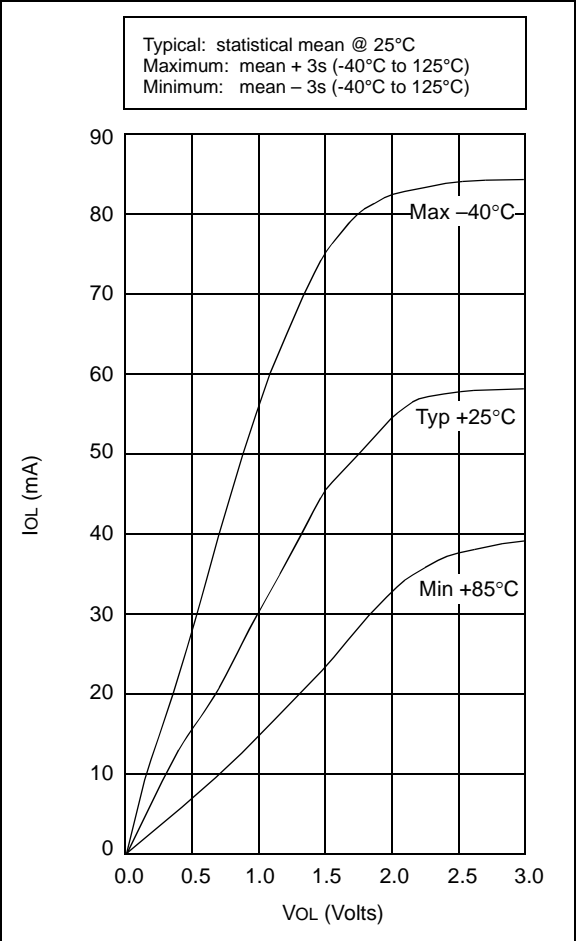


TABLE 18-2: INPUT CAPACITANCE

Pin	Typical Capacitance (pF)	
	18L PDIP	18L SOIC
RA port	5.0	4.3
RB port	5.0	4.3
MCLR	17.0	17.0
OSC1	4.0	3.5
OSC2/CLKOUT	4.3	3.5
T0CKI	3.2	2.8

All capacitance values are typical at 25°C. A part-to-part variation of ±25% (three standard deviations) should be taken into account.